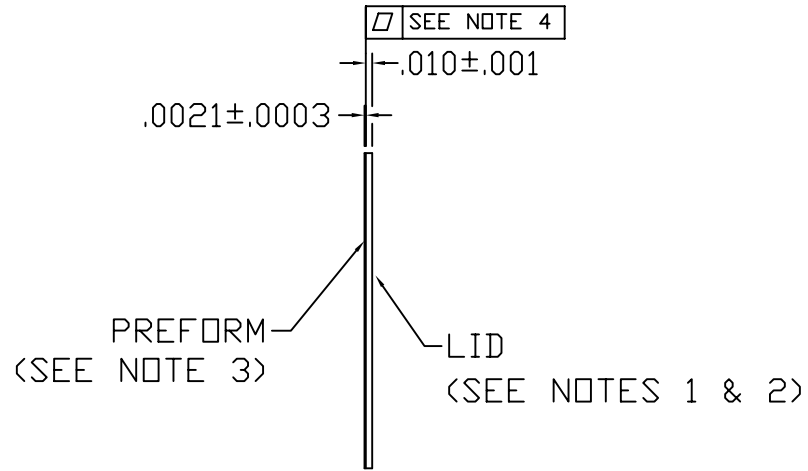
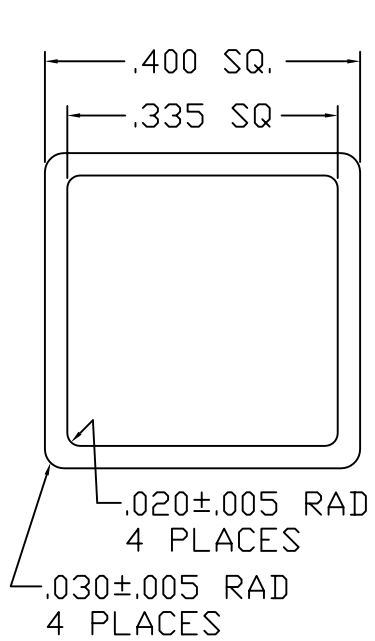


# SSM P/N CL-40009



**NOTES**

1. MAT'L : KOVAR OR ALLOY 42
  2. PLATING : 1st LAYER 50/350 MICROINCHES Ni  
2nd LAYER Au  
3rd LAYER 50/350 MICROINCHES Ni  
4th LAYER 25 MICROINCHES MINIMUM Au
  3. PREFORM - 80% ±1% Au  
20% Sn
  4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
  5. TOLERANCES TO BE (XXX) 3 PLACES ±.002 UNLESS OTHERWISE NOTED
- NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

DESCRIPTION		HI REL COMBO LID	
PART NO		CL-40009	
Spectrum Semiconductor Materials, Inc. 2027 O'Toole Ave San Jose, CA 95131 PH: (408) 435-5555 Fx: (408)435-8226		MFG WILLIAMS ADVANCED MATERIALS	
		MFG DRAWING NO	
		HRC-456	

